Position Title:	Die Attach Operator			**Position # or Level :**	1-4
Department:	Operations		**Reports to:**	Production Supervisor	
Employment Status:	Full Time	**Pay Grade or salary range:**	(List the pay grade or salary range for this position)	**% Travel Required**	NA

Position Summary: The Die Attach Operator is responsible for performing precision die attach operations in a cleanroom environment for microelectronic assemblies. This includes the placement and bonding of semiconductor chips, sensors, and other microcomponents onto substrates or packages using manual or semi-automated die attach equipment.

Essential Duties:

- Set up, operate, and monitor die attach equipment (manual, semi-auto bonders).
- Handle and align semiconductor dies, sensors, and other microcomponents under a microscope.
- Apply bonding materials (e.g., conductive epoxy, eutectic solder, or adhesive films) accurately and uniformly.
- Verify die placement accuracy, bond line thickness, and epoxy coverage using inspection microscopes.
- Perform thermal curing, reflow, or eutectic bonding per process specifications.
- Conduct in-process and final visual inspection for defects such as misalignment, voids, or contamination.
- Maintain detailed process logs, batch records, and yield reports.
- Support process improvement and engineering validation activities.

Other Duties & Responsibilities (Optional)

- N/A

Minimum Qualifications: H.S. Diploma or equivalent. Must be able to read and write English. Must be able to work with under a microscope.

1–3 years in semiconductor or microelectronics assembly, specifically in die attach, wire bond, or hybrid module assembly.

Key Competencies:

- Proficient in microscope-based assembly work with excellent hand-eye coordination.
- Familiarity with epoxy dispensing, eutectic attach, or solder reflow processes.
- Knowledge of handling small dies (100 µm to several mm) and delicate substrates (ceramic, PCB, or metal base).

Preferred Skills:

- Prior experience in contract manufacturing clean room environment.
- Experience with eutectic attach (AuSn, AuGe) using Westbond die bonders.

Work Environment: Indoors, environmentally controlled. Wear common ESD and protective equipment as necessary (i.e. safety glasses, gloves). While performing the duties of the job, the employee is regularly required to sit, stand and/or walk for extended periods of time; use hands and

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fingers; reach with hands and arms; and talk and hear. Specific vision abilities required by this job include close vision, color vision, peripheral vision, depth perception, and the ability to adjust focus.

Approvals Include required signatures here.

Name	**Title**	**Date**
Name	**Title**	**Date**